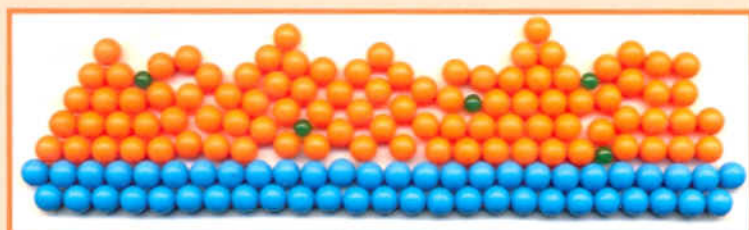


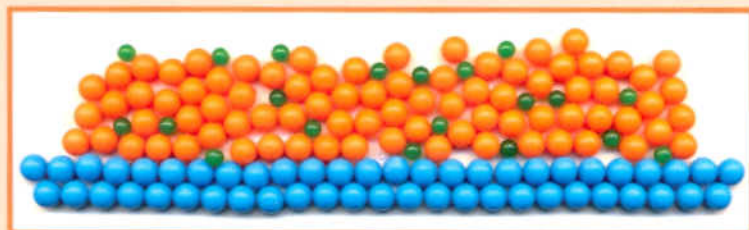


NANO-PLATING

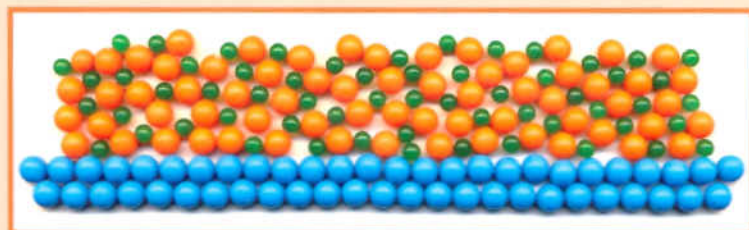
Microstructure Control Theory of
Plated Film and Data Base of Plated
Film Microstructure



Atomic ratio 95 : 5 Crystalline



Atomic ratio 80 : 20 Amorphous like



Atomic ratio 50 : 50 Amorphous

TOHRU WATANABE

Nano-Plating

Microstructure Control Theory of Plated Film and Data Base of Plated Film Microstructure

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